

► DESCRIPTION

The UM9301 PIN Diode utilizes special overall chip geometry with an extremely thick intrinsic "I" region, to offer unique capabilities in both RF switch and attenuator applications. Volume production also makes the diode an economical choice suitable for many commercial low power equipments. The UM9301 has been designed for use in bridged TEE attenuator circuits commonly utilized for gain and slope control in CATV amplifiers.

The UM9301 is also appropriate for switch applications, when little or no bias voltage is available. Frequent applications occur in portable 12 volt-powered communications equipments, operating at frequencies as low as 2 MHz.

► KEY FEATURES

- Low Distortion, even a low bias
- High Reliability Design
- Series resistance (R_s) specified at 3 current points.
- Available with RoHS compliant finish.

ABSOLUTE MAXIMUM RATINGS AT 25° C (UNLESS OTHERWISE SPECIFIED)

Rating	Symbol	Value	Unit
Reverse Voltage	VR	75	Volts
Reverse Current	IR	10	uA
Average Power Dissipation (1, 2)	PA	1.0	Watts
Storage Temperature	T _{STG}	-65 to 175	°C
Operating Temperature	T _{OP}	-65 to 175	°C

1. Mounted on 2" square by 0.06' thick FR4 board with a 1" x 1" square 2-ounce copper pattern.
2. Lead 1/2 inch. (12.7mm) Total to 25°C Contact.

► APPLICATIONS/BENEFITS

- Little or no bias required
- Operates as low as 2 MHz
- Available in Leaded or Surface Mount package
- Soldering temperature: 260 °C for 20 seconds maximum

UM9301



UM9301SM



IMPORTANT:

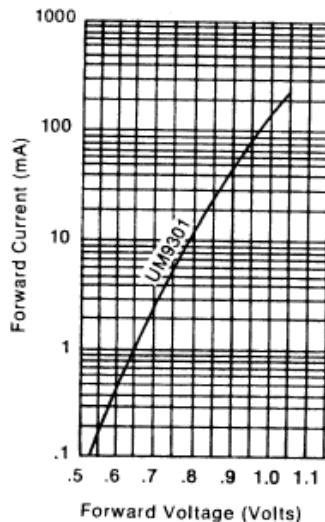
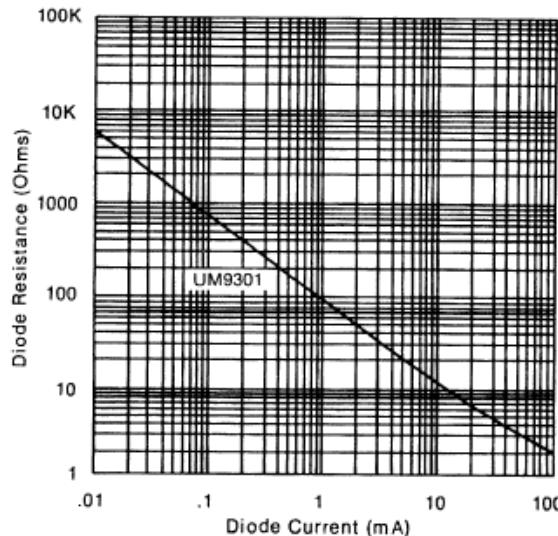
For the most current data, consult MICROSEMI's website: www.MICROSEMI.com

¹ The UM9301 can be supplied with a RoHS compliant matte Tin finish (UMX9301) or with a 90/10 Sn/Pb finish. Consult factory for details.

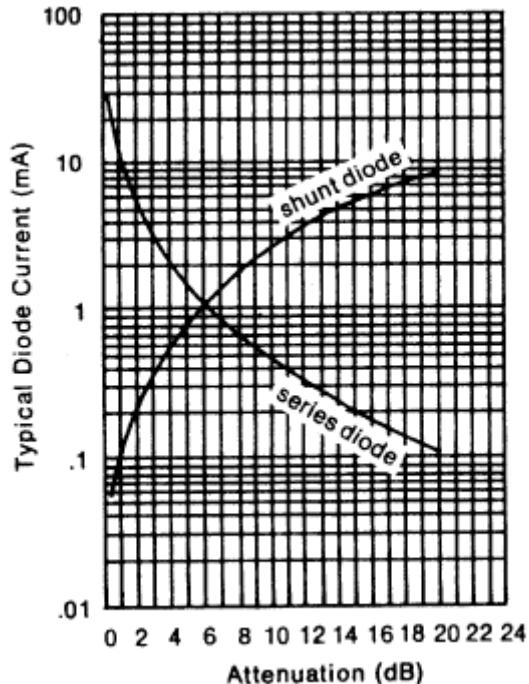
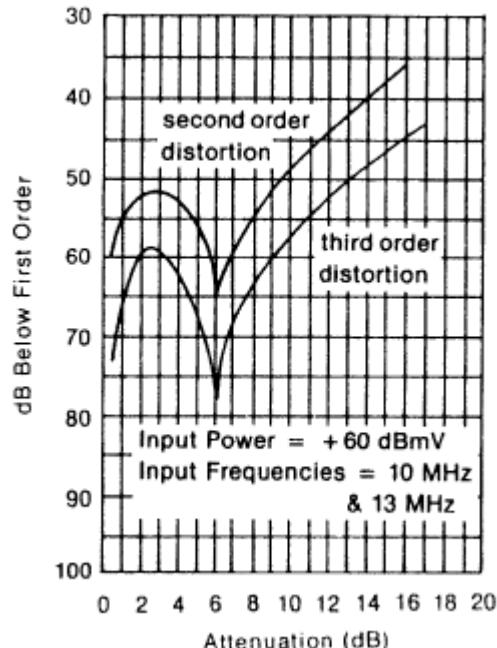
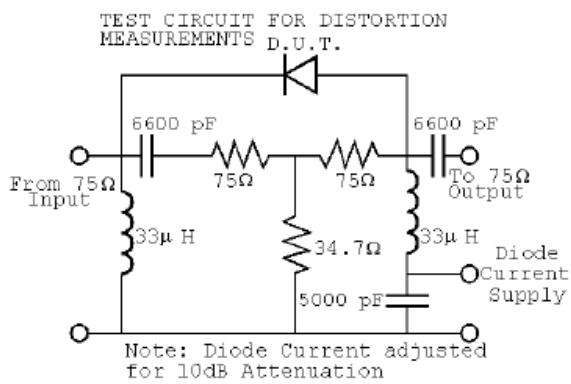
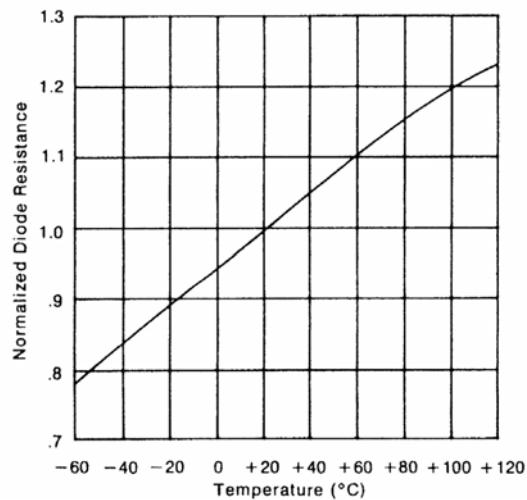


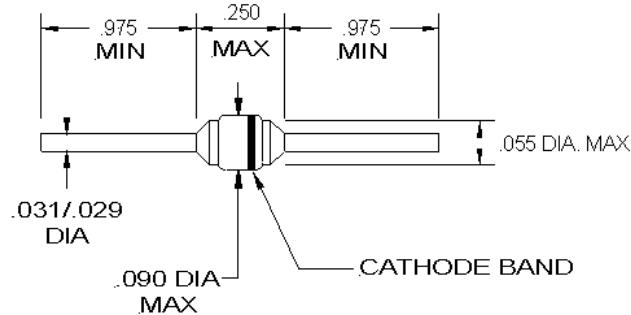
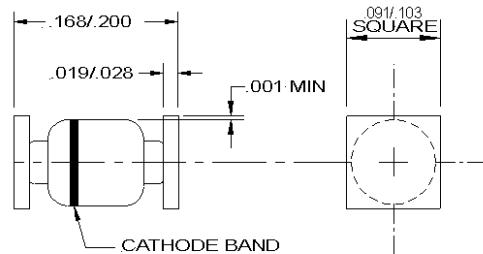
ELECTRICAL PARAMETERS @ 25°C (unless otherwise specified)

Parameter	Symbol	Conditions	MIN	TYP.	MAX	Units
Capacitance	C_T	$V = 0 \text{ V}; f = 100 \text{ MHz}$			0.8	pF
Diode Resistance	R_S	$I = 100 \text{ mA}; f = 100 \text{ MHz}$		1.7		Ω
		$I = 1 \text{ mA}; f = 100 \text{ MHz}$		80	150	
		$I = 0.01 \text{ mA}; f = 100 \text{ MHz}$	3000	5000		
Current for $R_S = 75 \Omega$	I_F	$f = 100 \text{ MHz}$	0.5	1.1	2.0	mA
Return Loss	I	Frequency Range: 10-300MHz $R_S = 75 \Omega @ 100\text{MHz}$ Diode Terminates 75Ω line	25			dB
Second Order Distortion	P_d	$f_1 = 10 \text{ MHz}; f_2 = 13 \text{ MHz}$ $P = 50 \text{ dBmV}; \text{See Test Circuit}$		55	50	-dB
		$f_1 = 67 \text{ MHz}; f_2 = 77 \text{ MHz}$ $P = 50 \text{ dBmV}; \text{See Test Circuit}$		70		
Third Order Distortion		$f_1 = 10 \text{ MHz}; f_2 = 13 \text{ MHz}$ $P = 50 \text{ dBmV}; \text{See Test Circuit}$		75	65	-dB
		Triple Beat; 205 +67 – 77MHz $P = 50 \text{ dBmV}; \text{See Test Circuit}$		95		
Cross Modulation Distortion		12 Channel Test $P = 50 \text{ dBmV}; \text{See Test Circuit}$ Dix Hills Test Set		75		-dB
Reverse Current	I_R	$V = 75 \text{ V}$			10	mA
Carrier Lifetime	τ	$I = 10 \text{ mA}$	4.0			uS

TYPICAL VF VS IF

TYPICAL RS VS IF


RoHS Compliant Versions Available

IF VS ATTENUATION

DISTORTION VS ATTENUATION

TYPICAL TEST CIRCUIT

NORMALIZED RS VS TEMP

TYPICAL BRIDGED 'T' ATTENUATOR PERFORMANCE

UM9301 (STYLE 'A')

UM9301SM (STYLE 'SM')

'SM' SOLDER NOTES

- 1- The solder footprint will match the terminals and provide for an optimal solder fillet assuming the accuracy of the device placement is within 0.005 inches.
- 2- This footprint provides for an optional adhesive, separate from the solder compound if desired.
- 3- Dimensions are in inches.

STYLE 'SM' FOOTPRINT
